

Applic. No. 10/765,584
Amdt. dated March 6, 2006
Reply to Office action of December 5, 2005

Claim Amendments

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended): A method for encapsulating a plurality of electronic components, which comprises:

joining a plurality of components together;

coating the plurality of components at the same time for providing the plurality of components with a coating of a flowable coating material;

hardening the material of the coating;

subjecting the assembly including the plurality of components and the coating to at least one further process operation, the at least one further process operation being a welding of the plurality of components to a conductor comb; and

subsequent to the welding of the plurality of components to a conductor comb, completely encapsulating the assembly of the plurality of components and the coating in plastic.

Applic. No. 10/765,584
Amdt. dated March 6, 2006
Reply to Office action of December 5, 2005

Claim 2 (previously presented): The method according to claim 1, which further comprises applying the coating material to the plurality of components by immersion.

Claim 3 (previously presented): The method according to claim 1, which further comprises carrying out the coating providing step by immersing the plurality of components in the coating material.

Claim 4 (previously presented): The method according to claim 1, which further comprises applying the coating material to the plurality of components by spraying.

Claim 5 (previously presented): The method according to claim 1, which further comprises carrying out the coating providing step by spraying the coating material on the plurality of components.

Claim 6-7 (cancelled).

Claim 8 (previously presented): The method according to claim 1, which further comprises carrying out the coating providing step by applying the coating material to the plurality of components by several successive coating operations.

Applic. No. 10/765,584
Amdt. dated March 6, 2006
Reply to Office action of December 5, 2005

Claim 9 (original): The method according to claim 1, which further comprises carrying out the hardening step by supplying external heat.

Claim 10 (original): The method according to claim 1, which further comprises carrying out the hardening step by heating the coating.

Claim 11 (original): The method according to claim 1, which further comprises carrying out the hardening step by drying under environmental conditions.

Claim 12 (original): The method according to claim 1, which further comprises providing coating material of the coating with a high coefficient of expansion and good adhesion properties.

Claim 13 (original): The method according to claim 12, which further comprises selecting the coating material from a plastic selected from the group consisting of polyurethane and silicone.

Claim 14 (original): The method according to claim 1, which further comprises selecting the coating material from a

Applic. No. 10/765,584
Amdt. dated March 6, 2006
Reply to Office action of December 5, 2005

plastic selected from the group consisting of polyurethane and silicone.

Claim 15 (cancelled).

Claim 16 (original): The method according to claim 1, which further comprises carrying out the plastic encapsulating step by injection molding the assembly with PBT.

Claim 17 (original): The method according to claim 1, which further comprises carrying out the plastic encapsulating step by encapsulating the assembly by injection molding PBT.

Claims 18-21 (cancelled).

Claim 22 (currently amended): The method according to claim [[21]] 1, wherein the completely encapsulating step is achieved by injection molding.

Claim 23 (previously presented): The method according to claim 22, further comprising separating the plurality of components by separating the conductor comb and encapsulating the separated components with a further encapsulation by injection molding.